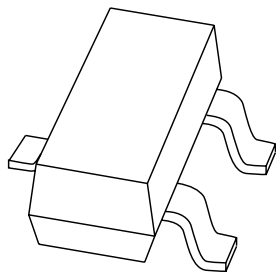


# DATA SHEET



## **PMBTA64** PNP Darlington transistor

Product data sheet  
Supersedes data of 2002 Nov 07

2004 Jan 22

# PNP Darlington transistor

## PMBTA64

### FEATURES

- High current (max. 500 mA)
- Low voltage (max. 30 V)
- High DC current gain (min. 10000).

### APPLICATIONS

- High input impedance preamplifiers.

### DESCRIPTION

PNP Darlington transistor in a SOT23 plastic package.  
NPN complement: PMBTA14.

### MARKING

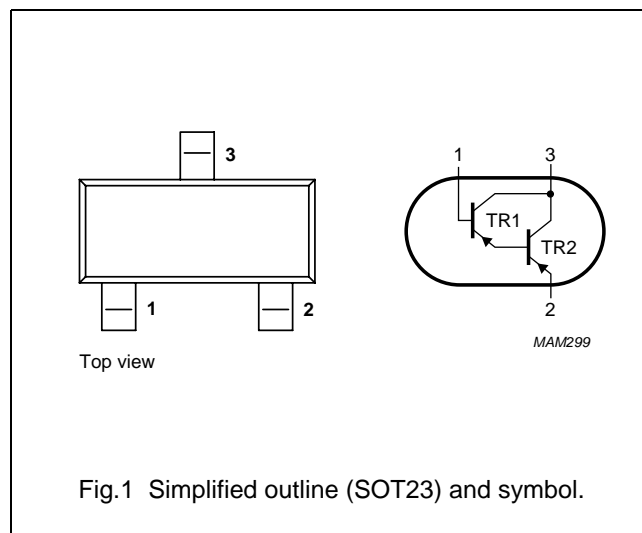
TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PMBTA64	*2V

### Note

- \* = p : Made in Hong Kong.  
\* = t : Made in Malaysia.  
\* = W : Made in China.

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PMBTA64	—	plastic surface mounted package; 3 leads	SOT23

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	—	−30	V
$V_{CES}$	collector-emitter voltage	$V_{BE} = 0$	—	−30	V
$V_{EBO}$	emitter-base voltage	open collector	—	−10	V
$I_C$	collector current (DC)		—	−500	mA
$I_{CM}$	peak collector current		—	−800	mA
$I_B$	base current (DC)		—	−200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ ; note 1	—	250	mW
$T_{stg}$	storage temperature		−65	+150	°C
$T_j$	junction temperature		—	150	°C
$T_{amb}$	operating ambient temperature		−65	+150	°C

### Note

1. Transistor mounted on an FR4 printed-circuit board.

PNP Darlington transistor

PMBTA64

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

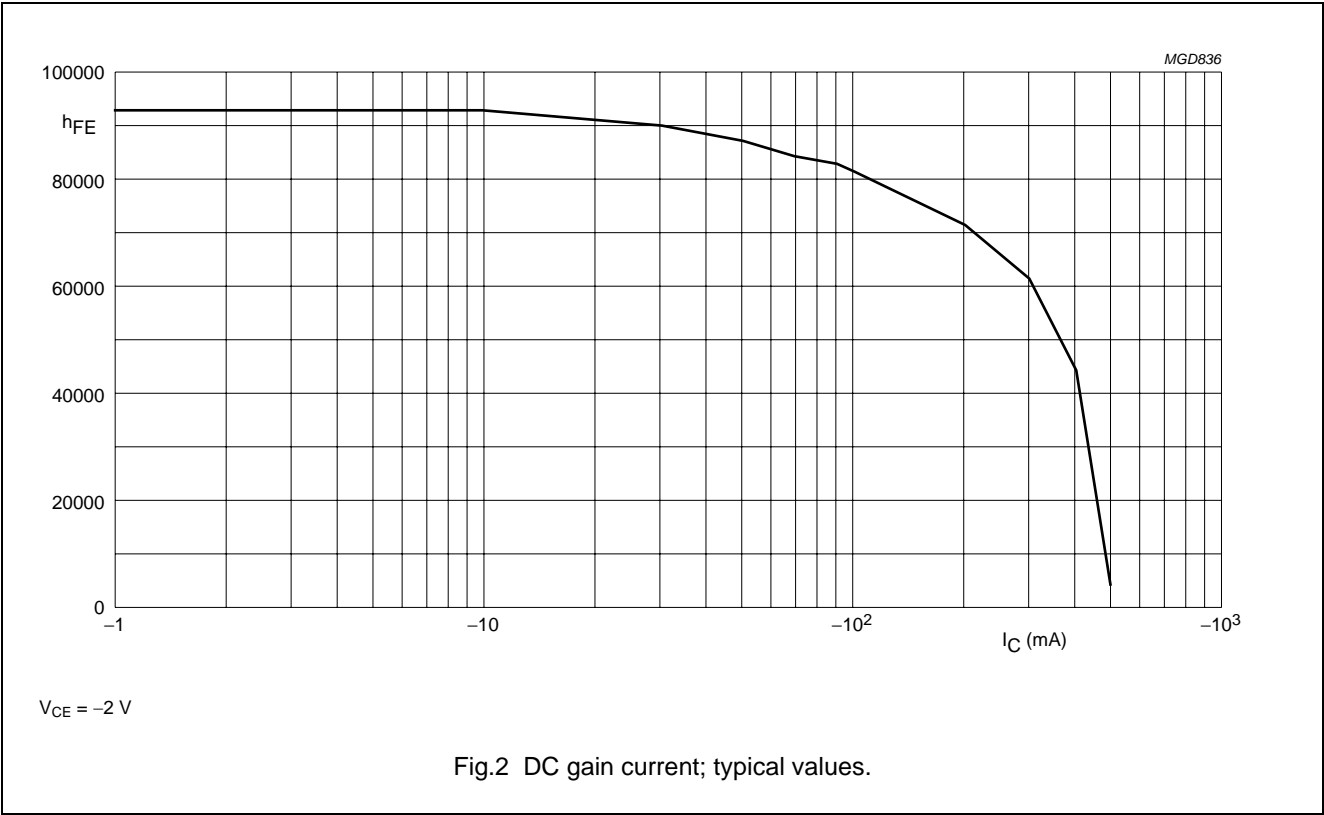
Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_j = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0$ ; $V_{CB} = -30\text{ V}$	–	–100	nA
$I_{EBO}$	emitter cut-off current	$I_C = 0$ ; $V_{EB} = -10\text{ V}$ ;	–	–100	nA
$h_{FE}$	DC current gain	$I_C = -10\text{ mA}$ ; $V_{CE} = -5\text{ V}$ ; (see Fig.2)	10000	–	
		$I_C = -100\text{ mA}$ ; $V_{CE} = -5\text{ V}$ ; (see Fig.2)	20000	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -100\text{ mA}$ ; $I_B = -0.1\text{ mA}$	–	–1.5	V
$V_{BEon}$	base-emitter on-state voltage	$I_C = -100\text{ mA}$ ; $V_{CE} = -5\text{ V}$	–	–2	V
$f_T$	transition frequency	$I_C = -50\text{ mA}$ ; $V_{CE} = -5\text{ V}$ ; $f = 100\text{ MHz}$	125	–	MHz



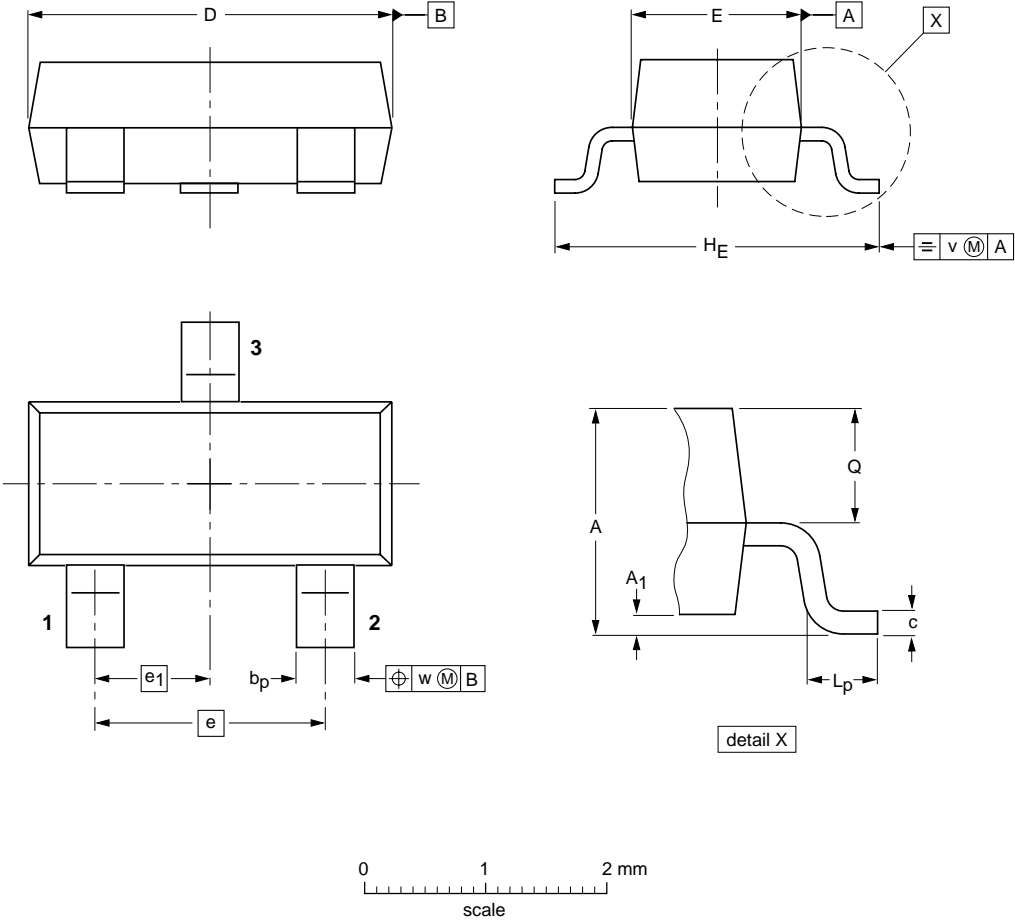
PNP Darlington transistor

PMBTA64

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max.	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

## PNP Darlington transistor

## PMBTA64

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

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